



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

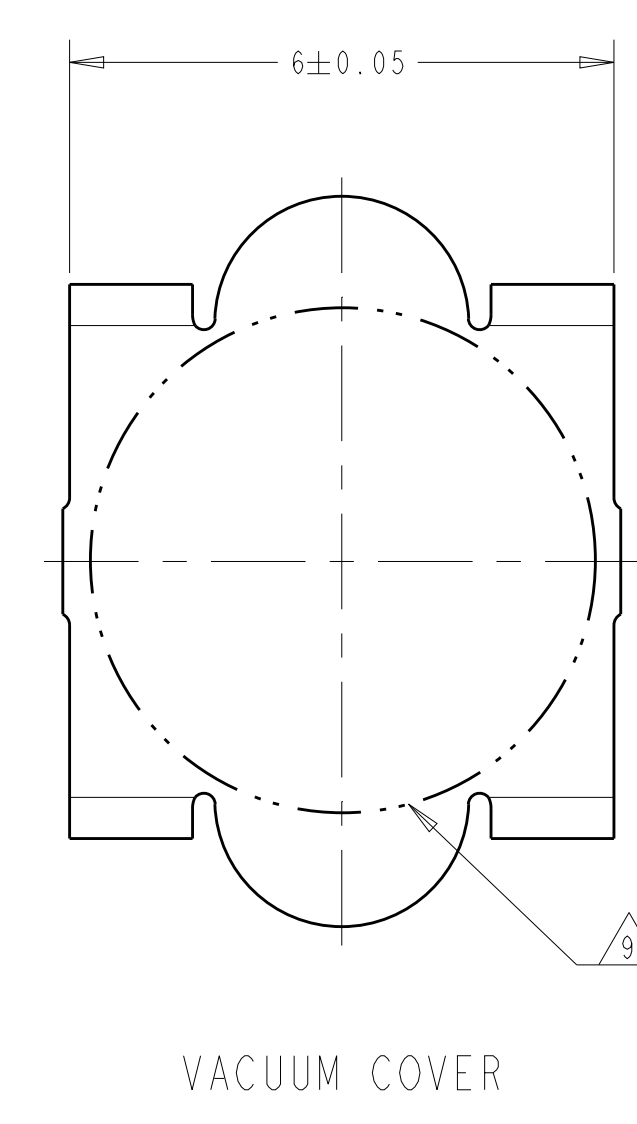
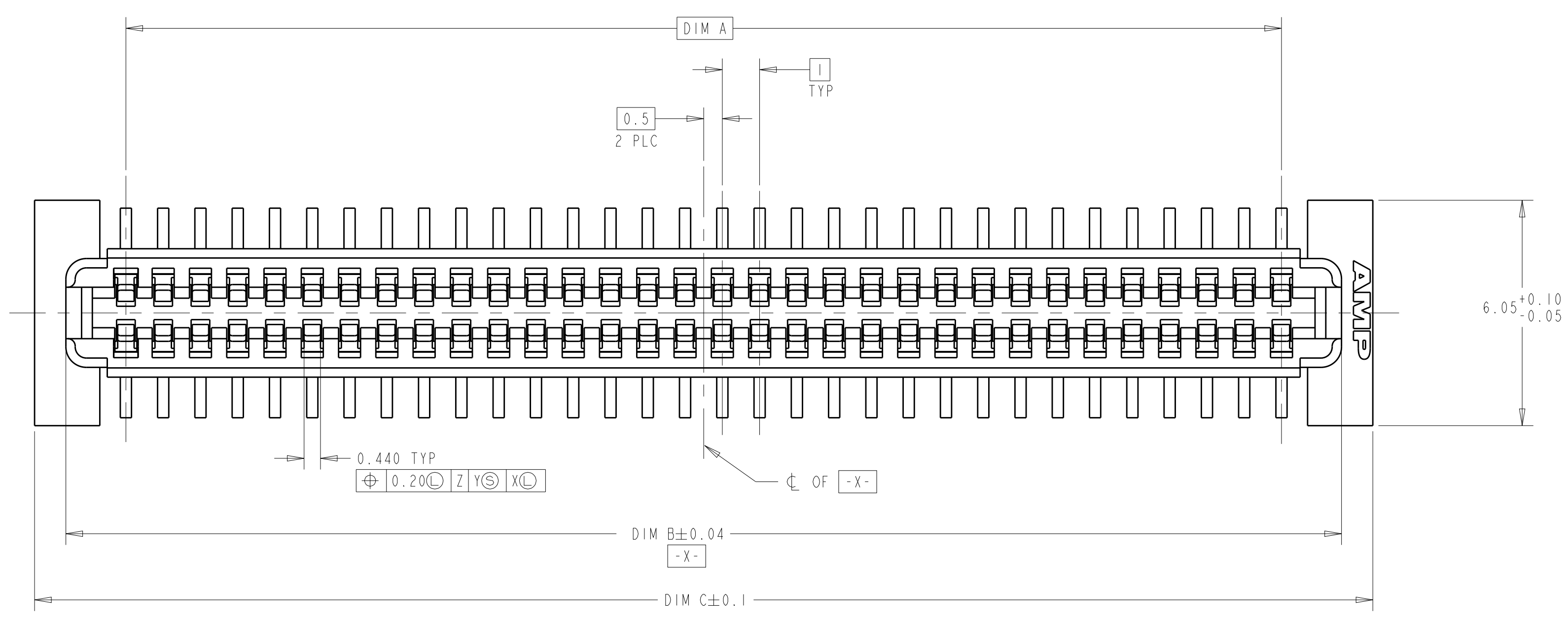
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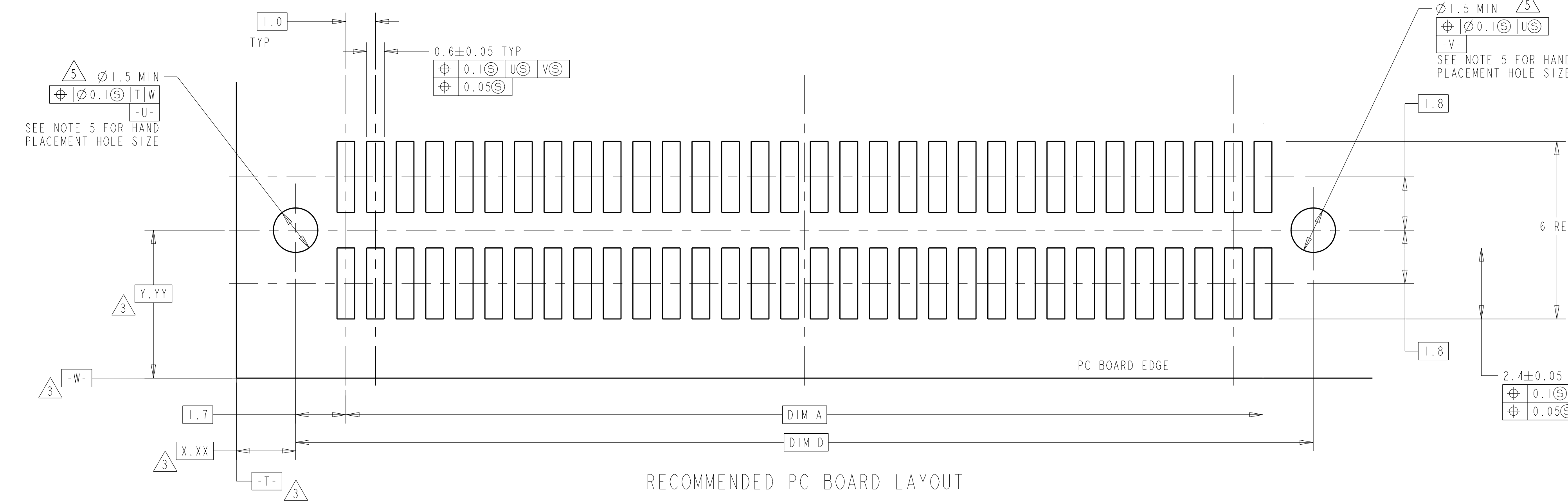
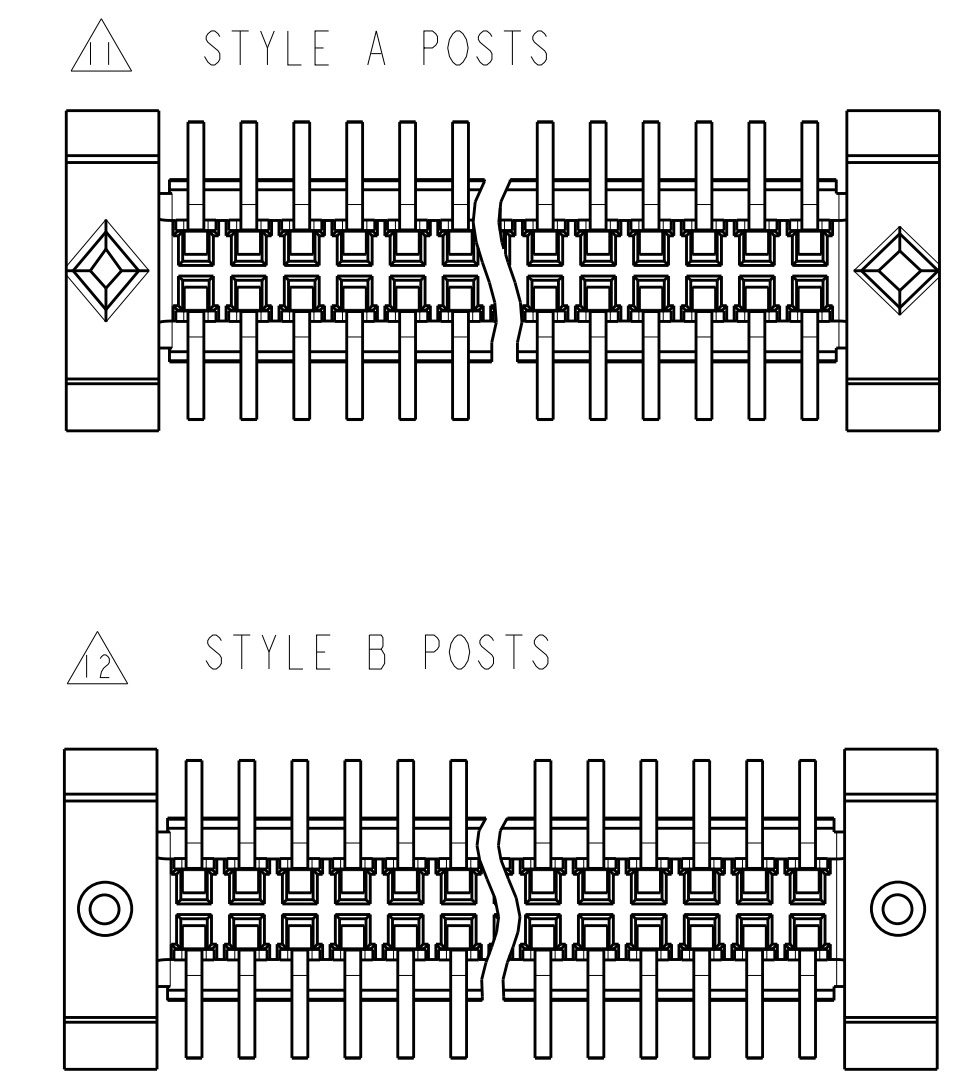
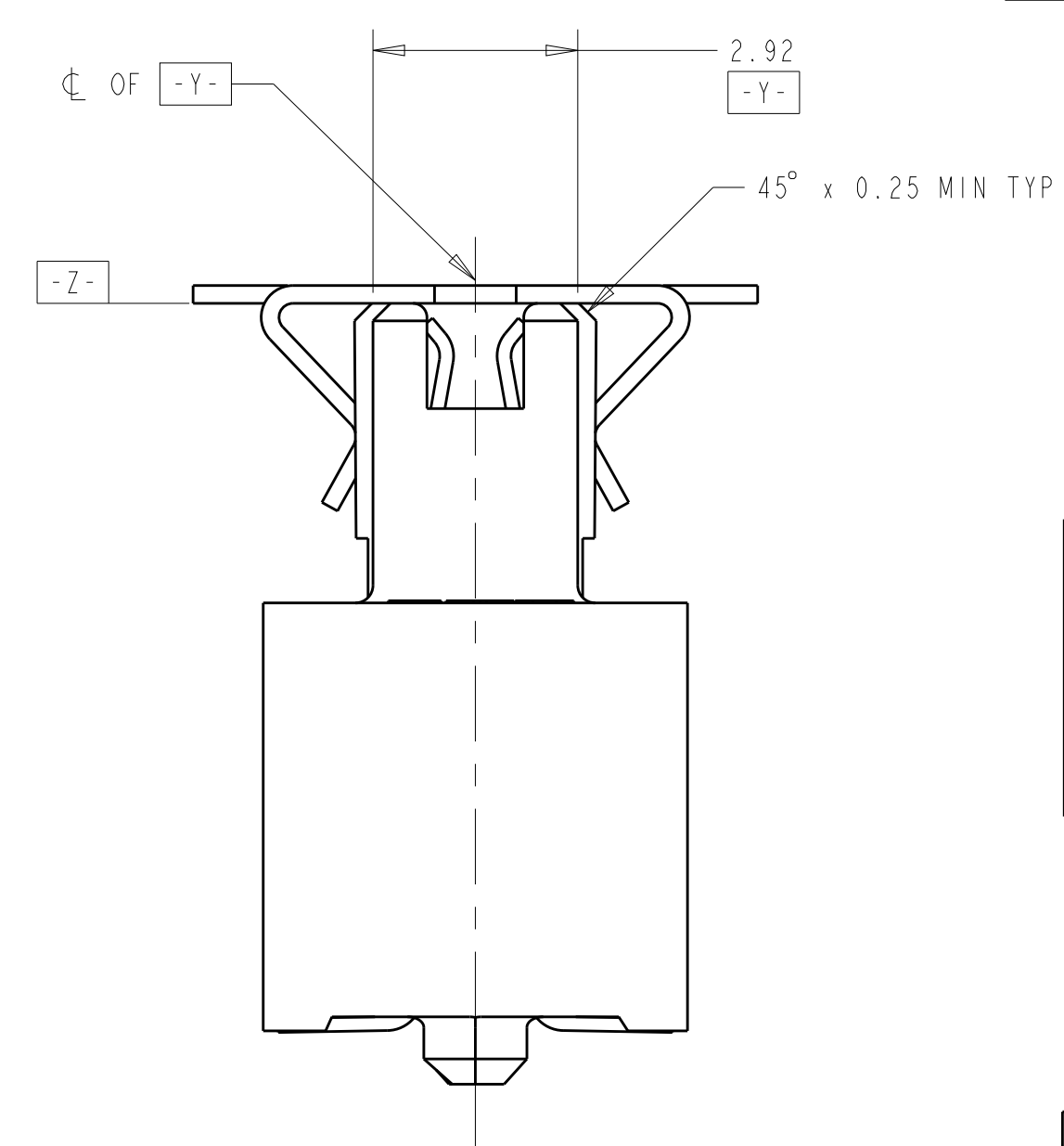
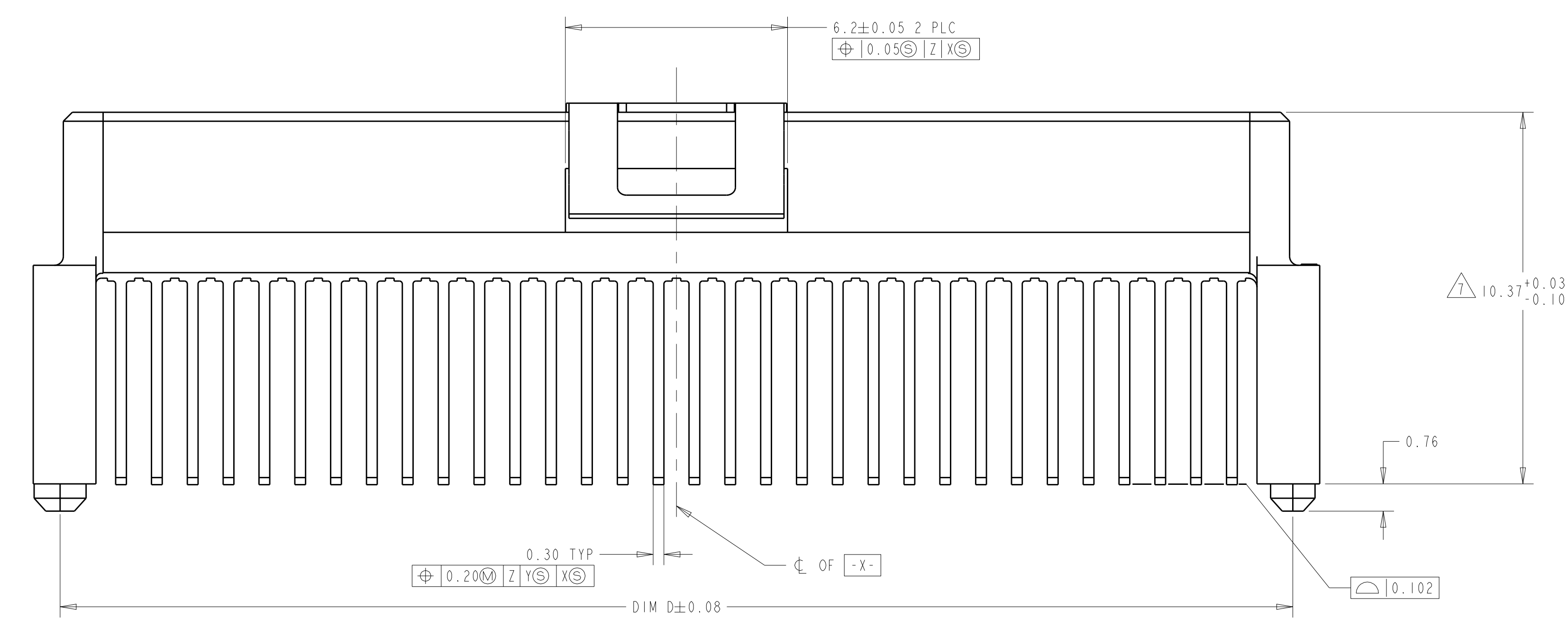
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REVISIONS				
P.	LTN.	DESCRIPTION	DATE	OWN. APVD.
M		REV PER ECR-14-016951	11FEB2015	J.T. W.H.



1. HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
2. CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN-LEAD.
3. DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
4. PACKAGED IN TAPE ON REEL PER EIA-481.
5. 1.4±0.05 DIAMETER HOLE WHEN PLACING BY HAND.
6. SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
7. REFERRED TO AS DIM H = 5.30±0.1 IN EIA 700AAAB SPECIFICATION.
8. VACUUM COVER NOT SHOWN IN SOME VIEWS FOR CLARITY.
9. 5.5 MIN DIAMETER TARGET AREA FOR VACUUM PICK-UP.
10. CONTACT FINISH: 0.002 MINIMUM BRIGHT TIN-LEAD (93-7) ON SOLDER AREA. 0.00127 MINIMUM GOLD ON MATING AREA. BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.
11. SQUARE AND DIAMOND SHAPED POSTS.
12. ROUND SHAPED POSTS.



POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HEIGHTS	POS	AMP PART NUMBER
12	10	44.4	45.9	44.22	41	14, 15	84	3-146896-2
12	10	34.4	35.9	34.22	31	14, 15	64	3-146896-1
12	2	44.4	45.9	44.22	41	14, 15	84	2-146896-2
12	2	34.4	35.9	34.22	31	14, 15	64	2-146896-1
11	10	44.4	45.9	44.22	41	14, 15	84	1-146896-2
11	10	34.4	35.9	34.22	31	14, 15	64	1-146896-1
11	2	44.4	45.9	44.22	41	14, 15	84	146896-2
11	2	34.4	35.9	34.22	31	14, 15	64	146896-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWN: D.K. SCHRUM 01AUG98, CHN: CHAD BAKER 01AUG98. NAME: RECEPTACLE ASSY, W/ VACUUM COVER, 1.0mm FH (IEEE 1386) CONNECTOR. PRODUCT SPEC: 502-1079, APPLICATION SPEC: 114-25045, WEIGHT: -.

STE TE Connectivity

SCALE: 10:1 SHEET 1 OF 1 REV M